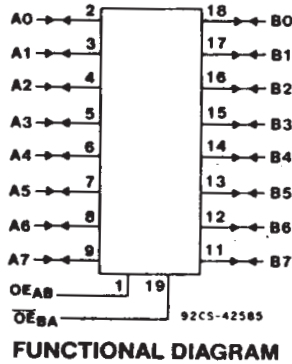


# CD54/74AC623 CD54/74ACT623



Data sheet acquired from Harris Semiconductor  
SCHS286A - October 2003



## Octal-Bus Transceiver, 3-State, Non-Inverting

**Type Features:**

- Buffered inputs
- Typical propagation delay:  
4.5 ns @  $V_{CC} = 5\text{ V}$ ,  $T_A = 25^\circ\text{C}$ ,  $C_L = 50\text{ pF}$

**Family Features:**

- Exceeds 2-kV ESD Protection - MIL-STD-883, Method 3015
- SCR-Latchup-resistant CMOS process and circuit design
- Speed of bipolar FAST\*/AS/S with significantly reduced power consumption
- Balanced propagation delays
- AC types feature 1.5-V to 5.5-V operation and balanced noise immunity at 30% of the supply
- $\pm 24\text{-mA}$  output drive current
  - Fanout to 15 FAST\* ICs
  - Drives 50-ohm transmission lines

\*FAST is a Registered Trademark of Fairchild Semiconductor Corp.

The RCA CD54/74AC623 and CD54/74ACT623 octal-bus transceivers use the RCA ADVANCED CMOS technology. They are non-inverting, 3-state, bidirectional transceiver-buffers that allow for two-way transmission from "A" bus to "B" bus or "B" bus to "A" bus, depending on the logic levels of the Output Enable ( $OE_{AB}$ ,  $OE_{BA}$ ) inputs.

The dual Output Enable provision gives these devices the capability to store data by simultaneously enabling  $OE_{AB}$  and  $OE_{BA}$ . Each output reinforces its input under these conditions, and when all other data sources to the bus lines are at high-impedance, both sets of bus lines will remain in their last states.

The CD74AC623 is supplied in 20-lead dual-in-line plastic packages (E suffix) and in 20-lead small-outline packages (M, M96, and NSR suffixes). The CD74ACT623 is supplied in 20-lead small-outline packages (M96 suffix). Both package types are operable over the following temperature ranges: Commercial (0 to 70°C); Industrial (-40 to +85°C); and Extended Industrial/Military (-55 to +125°C).

The CD54AC623 and CD54ACT623, available in chip form (H suffix), are operable over the -55 to +125°C temperature range.

**TRUTH TABLE**

OUTPUT ENABLE INPUTS		OPERATION
$OE_{BA}$	$OE_{AB}$	
L	L	B DATA TO A BUS
H	H	A DATA TO B BUS
H	L	ISOLATION
L	H	B DATA TO A BUS, A DATA TO B BUS

H = High level, L = Low level

Note: To prevent excess currents in the High-Z (isolation) modes, all I/O terminals should be terminated with 10 kΩ to 1 MΩ resistors.

This data sheet is applicable to the CD74AC623 and CD54/74ACT623. The CD54AC623 was not acquired from Harris Semiconductor.

# Technical Data

## CD54/74AC623

## CD54/74ACT623

### MAXIMUM RATINGS, Absolute-Maximum Values:

DC SUPPLY-VOLTAGE ( $V_{CC}$ )	.....	-0.5 to 6 V
DC INPUT DIODE CURRENT, $I_{IK}$ (for $V_I < -0.5$ V or $V_I > V_{CC} + 0.5$ V)	.....	$\pm 20$ mA
DC OUTPUT DIODE CURRENT, $I_{OK}$ (for $V_O < -0.5$ V or $V_O > V_{CC} + 0.5$ V)	.....	$\pm 50$ mA
DC OUTPUT SOURCE OR SINK CURRENT per Output Pin, $I_O$ (for $V_O > -0.5$ V or $V_O < V_{CC} + 0.5$ V)	.....	$\pm 50$ mA
DC $V_{CC}$ or GROUND CURRENT ( $I_{CC}$ or $I_{GND}$ )	.....	$\pm 100$ mA*
POWER DISSIPATION PER PACKAGE ( $P_D$ ):		
For $T_A = -55$ to $+100^\circ\text{C}$ (PACKAGE TYPE E)	.....	500 mW
For $T_A = +100$ to $+125^\circ\text{C}$ (PACKAGE TYPE E)	.....	Derate Linearly at 8 mW/ $^\circ\text{C}$ to 300 mW
For $T_A = -55$ to $+70^\circ\text{C}$ (PACKAGE TYPE M)	.....	400 mW
For $T_A = +70$ to $+125^\circ\text{C}$ (PACKAGE TYPE M)	.....	Derate Linearly at 6 mW/ $^\circ\text{C}$ to 70 mW
OPERATING-TEMPERATURE RANGE ( $T_A$ )	.....	-55 to $+125^\circ\text{C}$
STORAGE TEMPERATURE ( $T_{STG}$ )	.....	-65 to $+150^\circ\text{C}$
LEAD TEMPERATURE (DURING SOLDERING):		
At distance $1/16 \pm 1/32$ in. ( $1.59 \pm 0.79$ mm) from case for 10 s maximum	.....	$+265^\circ\text{C}$
Unit inserted into PC board min. thickness $1/16$ in. (1.59 mm) with solder contacting lead tips only	.....	$+300^\circ\text{C}$

\*For up to 4 outputs per device; add  $\pm 25$  mA for each additional output.

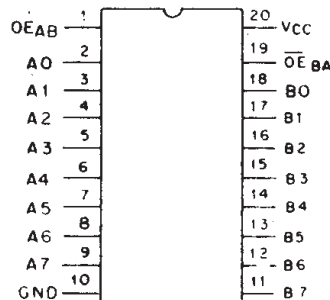
### RECOMMENDED OPERATING CONDITIONS:

For maximum reliability, normal operating conditions should be selected so that operation is always within the following ranges:

CHARACTERISTIC	LIMITS		UNITS
	MIN.	MAX.	
Supply-Voltage Range, $V_{CC}$ *: (For $T_A =$ Full Package-Temperature Range)			
AC Types	1.5	5.5	V
ACT Types	4.5	5.5	V
DC Input or Output Voltage, $V_I, V_O$	0	$V_{CC}$	V
Operating Temperature, $T_A$	-55	+125	$^\circ\text{C}$
Input Rise and Fall Slew Rate, $dt/dv$			
at 1.5 V to 3 V (AC Types)	0	50	ns/V
at 3.6 V to 5.5 V (AC Types)	0	20	ns/V
at 4.5 V to 5.5 V (ACT Types)	0	10	ns/V

\*Unless otherwise specified, all voltages are referenced to ground.

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92CS 4258C

### TERMINAL ASSIGNMENT

# CD54/74AC623

## CD54/74ACT623

STATIC ELECTRICAL CHARACTERISTICS: AC Series

CHARACTERISTICS	TEST CONDITIONS		V <sub>CC</sub> (V)	AMBIENT TEMPERATURE (T <sub>A</sub> ) - °C						UNITS
				+25		-40 to +85		-55 to +125		
	V <sub>I</sub> (V)	I <sub>O</sub> (mA)		MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	
High-Level Input Voltage V <sub>IH</sub>			1.5	1.2	—	1.2	—	1.2	—	V
			3	2.1	—	2.1	—	2.1	—	
			5.5	3.85	—	3.85	—	3.85	—	
Low-Level Input Voltage V <sub>IL</sub>			1.5	—	0.3	—	0.3	—	0.3	V
			3	—	0.9	—	0.9	—	0.9	
			5.5	—	1.65	—	1.65	—	1.65	
High-Level Output Voltage V <sub>OH</sub>	V <sub>IH</sub> or V <sub>IL</sub> #,*	-0.05	1.5	1.4	—	1.4	—	1.4	—	V
		-0.05	3	2.9	—	2.9	—	2.9	—	
		-0.05	4.5	4.4	—	4.4	—	4.4	—	
		-4	3	2.58	—	2.48	—	2.4	—	
		-24	4.5	3.94	—	3.8	—	3.7	—	
		-75	5.5	—	—	3.85	—	—	—	
		-50	5.5	—	—	—	—	3.85	—	
Low-Level Output Voltage V <sub>OL</sub>	V <sub>IH</sub> or V <sub>IL</sub> #,*	0.05	1.5	—	0.1	—	0.1	—	0.1	V
		0.05	3	—	0.1	—	0.1	—	0.1	
		0.05	4.5	—	0.1	—	0.1	—	0.1	
		12	3	—	0.36	—	0.44	—	0.5	
		24	4.5	—	0.36	—	0.44	—	0.5	
		75	5.5	—	—	—	1.65	—	—	
		50	5.5	—	—	—	—	—	1.65	
Input Leakage Current I <sub>I</sub>	V <sub>CC</sub> or GND		5.5	—	±0.1	—	±1	—	±1	μA
3-State Leakage Current I <sub>OZ</sub>	V <sub>IH</sub> or V <sub>IL</sub> V <sub>O</sub> = V <sub>CC</sub> or GND		5.5	—	±0.5	—	±5	—	±10	μA
Quiescent Supply Current, MSI I <sub>CC</sub>	V <sub>CC</sub> or GND	0	5.5	—	8	—	80	—	160	μA

#Test one output at a time for a 1-second maximum duration. Measurement is made by forcing current and measuring voltage to minimize power dissipation.

\*Test verifies a minimum 50-ohm transmission-line-drive capability at +85°C, 75 ohms at +125°C.

Technical Data  
**CD54/74AC623**  
**CD54/74ACT623**

STATIC ELECTRICAL CHARACTERISTICS: ACT Series

CHARACTERISTICS	TEST CONDITIONS		V <sub>CC</sub> (V)	AMBIENT TEMPERATURE (T <sub>A</sub> ) - °C						UNITS
				+25		-40 to +85		-55 to +125		
	V <sub>I</sub> (V)	I <sub>O</sub> (mA)		MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	
High-Level Input Voltage V <sub>IH</sub>			4.5 to 5.5	2	—	2	—	2	—	V
Low-Level Input Voltage V <sub>IL</sub>			4.5 to 5.5	—	0.8	—	0.8	—	0.8	V
High-Level Output Voltage V <sub>OH</sub>	V <sub>IH</sub> or V <sub>IL</sub> #,*	-0.05	4.5	4.4	—	4.4	—	4.4	—	V
		-24	4.5	3.94	—	3.8	—	3.7	—	
		-75	5.5	—	—	3.85	—	—	—	
		-50	5.5	—	—	—	—	3.85	—	
Low-Level Output Voltage V <sub>OL</sub>	V <sub>IH</sub> or V <sub>IL</sub> #,*	0.05	4.5	—	0.1	—	0.1	—	0.1	V
		24	4.5	—	0.36	—	0.44	—	0.5	
		75	5.5	—	—	—	1.65	—	—	
		50	5.5	—	—	—	—	—	1.65	
Input Leakage Current I <sub>I</sub>	V <sub>CC</sub> or GND		5.5	—	±0.1	—	±1	—	±1	μA
3-State Leakage Current I <sub>OZ</sub>	V <sub>IH</sub> or V <sub>IL</sub> V <sub>O</sub> = V <sub>CC</sub> or GND		5.5	—	±0.5	—	±5	—	±10	μA
Quiescent Supply Current, MSI I <sub>CC</sub>	V <sub>CC</sub> or GND	0	5.5	—	8	—	80	—	160	μA
Additional Quiescent Supply Current per Input Pin TTL Inputs High 1 Unit Load ΔI <sub>CC</sub>	V <sub>CC</sub> -2.1		4.5 to 5.5	—	2.4	—	2.8	—	3	mA

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#Test one output at a time for a 1-second maximum duration. Measurement is made by forcing current and measuring voltage to minimize power dissipation.

\*Test verifies a minimum 50-ohm transmission-line-drive capability at +85°C, 75 ohms at +125°C.

**ACT INPUT LOADING TABLE**

INPUT	UNIT LOAD*
An, Bn	0.83
$\overline{OE}_{BA}$	0.64
$\overline{OE}_{AB}$	0.15

\*Unit load is ΔI<sub>CC</sub> limit specified in Static Characteristics Chart, e.g., 2.4 mA max. @ 25°C.

Technical Data

# CD54/74AC623

# CD54/74ACT623

SWITCHING CHARACTERISTICS: AC Series;  $t_r, t_f = 3 \text{ ns}$ ,  $C_L = 50 \text{ pF}$

CHARACTERISTICS	SYMBOL	$V_{CC}$ (V)	AMBIENT TEMPERATURE ( $T_A$ ) - °C				UNITS
			-40 to +85		-55 to +125		
			MIN.	MAX.	MIN.	MAX.	
Propagation Delays: Data to Output	$t_{PLH}$	1.5	—	108	—	120	ns
	$t_{PHL}$	3.3* 5†	3.5 2.5	12.2 8.7	3.4 2.4	13.4 9.6	
Output Disable to Output	$t_{PLZ}$	1.5	—	153	—	168	ns
	$t_{PHZ}$	3.3 5	4.8 3.5	17.1 12.2	4.7 3.4	18.8 13.4	
Output Enable to Output	$t_{PZL}$	1.5	—	153	—	168	ns
	$t_{PZH}$	3.3 5	4.8 3.5	17.1 12.2	4.7 3.4	18.8 13.4	
Power Dissipation Capacitance	$C_{PD}\S$	—	66 Typ.		66 Typ.		pF
Min. (Valley) $V_{OH}$ During Switching of Other Outputs (Output Under Test Not Switching)	$V_{OHV}$ See Fig. 1	5	4 Typ. @ 25°C				V
Max. (Peak) $V_{OL}$ During Switching of Other Outputs (Output Under Test Not Switching)	$V_{OLP}$ See Fig. 1	5	1 Typ. @ 25°C				V
Input Capacitance	$C_i$	—	—	10	—	10	pF
3-State Output Capacitance	$C_o$	—	—	15	—	15	pF

SWITCHING CHARACTERISTICS: ACT Series;  $t_r, t_f = 3 \text{ ns}$ ,  $C_L = 50 \text{ pF}$

CHARACTERISTICS	SYMBOL	$V_{CC}$ (V)	AMBIENT TEMPERATURE ( $T_A$ ) - °C				UNITS
			-40 to +85		-55 to +125		
			MIN.	MAX.	MIN.	MAX.	
Propagation Delays: Data to Output	$t_{PLH}$ $t_{PHL}$	5†	2.7	9.6	2.7	10.6	ns
	Output Disable to Output	$t_{PLZ}$ $t_{PHZ}$	5	3.7	13.1	3.6	
Output Enable to Output		$t_{PZH}$ $t_{PZL}$	5	3.7	13.1	3.6	14.4
	Power Dissipation Capacitance	$C_{PD}\S$	—	66 Typ.		66 Typ.	
Min. (Valley) $V_{OH}$ During Switching of Other Outputs (Output Under Test Not Switching)	$V_{OHV}$ See Fig. 1	5	4 Typ. @ 25°C				V
Max. (Peak) $V_{OL}$ During Switching of Other Outputs (Output Under Test Not Switching)	$V_{OLP}$ See Fig. 1	5	1 Typ. @ 25°C				V
Input Capacitance	$C_i$	—	—	10	—	10	pF
3-State Output Capacitance	$C_o$	—	—	15	—	15	pF

\*3.3 V: min. is @ 3.6 V  
max. is @ 3 V

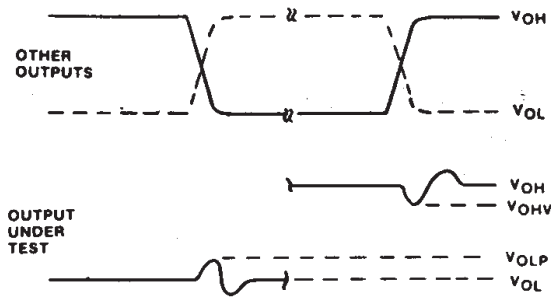
†5 V: min. is @ 5.5 V  
max. is @ 4.5 V

§ $C_{PD}$  is used to determine the dynamic power consumption, per channel.

For AC series:  $P_D = V_{CC}^2 f_i (C_{PD} + C_L)$

For ACT series:  $P_D = V_{CC}^2 f_i (C_{PD} + C_L) + V_{CC} \Delta I_{CC}$  where  $f_i$  = input frequency  
 $C_L$  = output load capacitance  
 $V_{CC}$  = supply voltage.

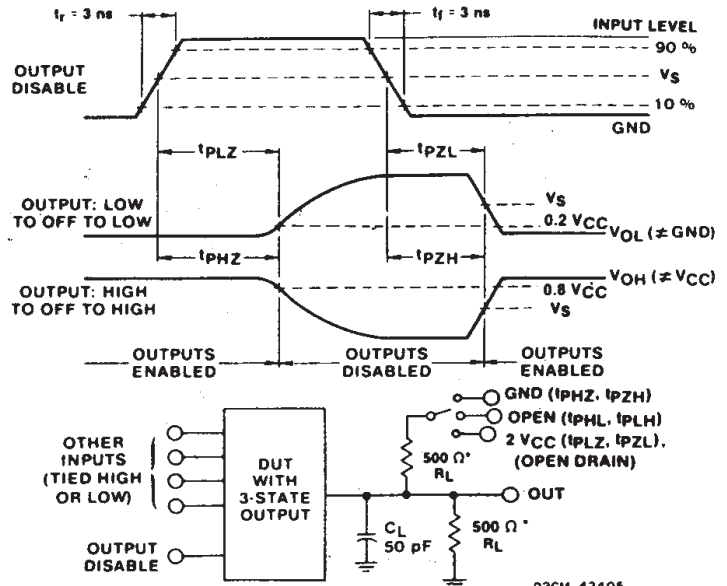
**PARAMETER MEASUREMENT INFORMATION**



- NOTES:
1.  $V_{OHV}$  and  $V_{OLP}$  ARE MEASURED WITH RESPECT TO A GROUND REFERENCE NEAR THE OUTPUT UNDER TEST.
  2. INPUT PULSES HAVE THE FOLLOWING CHARACTERISTICS:  
 $PRR \leq 1$  MHz,  $t_r = 3$  ns,  $t_f = 3$  ns, SKEW 1 ns.
  3. R.F. FIXTURE WITH 700-MHz DESIGN RULES REQUIRED. IC SHOULD BE SOLDERED INTO TEST BOARD AND BYPASSED WITH  $0.1 \mu\text{F}$  CAPACITOR. SCOPE AND PROBES REQUIRE 700-MHz BANDWIDTH.

92CS-4240E

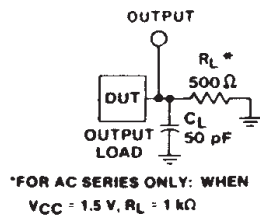
Fig. 1 - Simultaneous switching transient waveforms.



92CM-42405

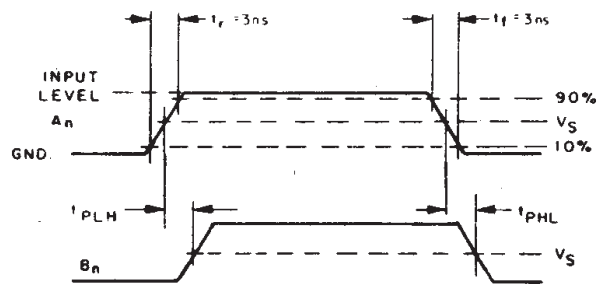
\*FOR AC SERIES ONLY: WHEN  $V_{CC} = 1.5$  V,  $R_L = 1$  k $\Omega$

Fig. 2 - Three-state propagation delay times and test circuit.



\*FOR AC SERIES ONLY: WHEN  $V_{CC} = 1.5$  V,  $R_L = 1$  k $\Omega$

92CS-42589



92CS-42587

Fig. 3 - Propagation delay times and test circuit.

	CD54/74AC	CD54/74ACT
Input Level	$V_{CC}$	3 V
Input Switching Voltage, $V_S$	$0.5 V_{CC}$	1.5 V
Output Switching Voltage, $V_S$	$0.5 V_{CC}$	$0.5 V_{CC}$

**PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
CD54ACT623F3A	ACTIVE	CDIP	J	20	1	TBD	Call TI	Level-NC-NC-NC
CD74AC623E	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
CD74AC623EE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
CD74AC623M	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74AC623M96	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74AC623M96E4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74AC623ME4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74AC623NSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74AC623NSRE4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74ACT623M96	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74ACT623M96E4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBsolete:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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J (R-GDIP-T\*\*)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package is hermetically sealed with a ceramic lid using glass frit.
  - D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
  - E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.



N (R-PDIP-T\*\*)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - $\triangle C$  Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
  - $\triangle D$  The 20 pin end lead shoulder width is a vendor option, either half or full width.

4040049/E 12/2002

DW (R-PDSO-G20)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
  - D. Falls within JEDEC MS-013 variation AC.

## MECHANICAL DATA

NS (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

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Amplifiers	<a href="http://amplifier.ti.com">amplifier.ti.com</a>	Audio	<a href="http://www.ti.com/audio">www.ti.com/audio</a>
Data Converters	<a href="http://dataconverter.ti.com">dataconverter.ti.com</a>	Automotive	<a href="http://www.ti.com/automotive">www.ti.com/automotive</a>
DSP	<a href="http://dsp.ti.com">dsp.ti.com</a>	Broadband	<a href="http://www.ti.com/broadband">www.ti.com/broadband</a>
Interface	<a href="http://interface.ti.com">interface.ti.com</a>	Digital Control	<a href="http://www.ti.com/digitalcontrol">www.ti.com/digitalcontrol</a>
Logic	<a href="http://logic.ti.com">logic.ti.com</a>	Military	<a href="http://www.ti.com/military">www.ti.com/military</a>
Power Mgmt	<a href="http://power.ti.com">power.ti.com</a>	Optical Networking	<a href="http://www.ti.com/opticalnetwork">www.ti.com/opticalnetwork</a>
Microcontrollers	<a href="http://microcontroller.ti.com">microcontroller.ti.com</a>	Security	<a href="http://www.ti.com/security">www.ti.com/security</a>
		Telephony	<a href="http://www.ti.com/telephony">www.ti.com/telephony</a>
		Video & Imaging	<a href="http://www.ti.com/video">www.ti.com/video</a>
		Wireless	<a href="http://www.ti.com/wireless">www.ti.com/wireless</a>

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